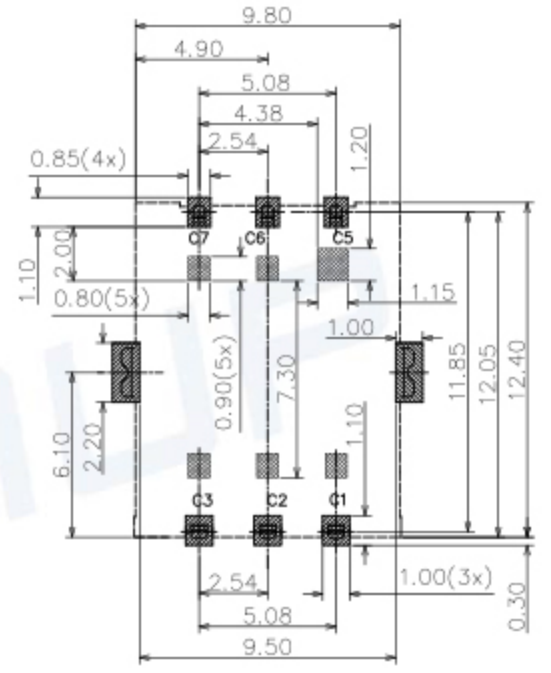
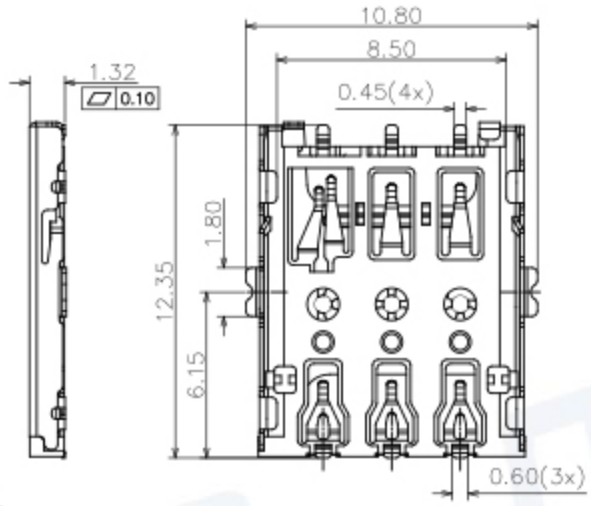
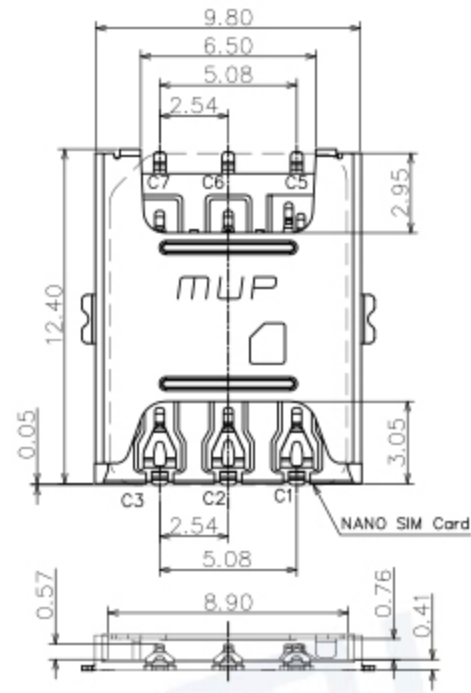


REV.	DESCRIPTION OF REVISIONS	APPR.	CHKD.	DRAW.	DATE
▲	NEW			Henry	2019/3/12
▲	Original Model C782-4			Henry	2023/10/19

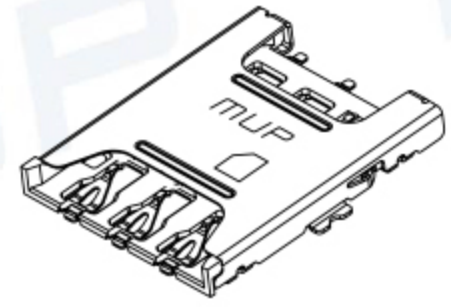


RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

- PAD AREA
- CONNECTOR OUTLINE
- NO DRILL PATTERN AND VIA HOLE IN THIS AREA

TECHNICAL CHARACTERISTICS

- 1.General Characteristics
Dimensions: 12.40LX9.80WX1.35H mm
Weight: Approx 0.50±0.2g
Durability: 1,500 cycles min.
- 2.Electrical Characteristics
Contact resistance: 50mΩ typical,
100mΩ max
Insulation resistance: >1000MΩ/500V DC
- 3.Solderability
Vaporphase: 215°C, 30sec. Max
IR reflow: 250°C, 5sec. Max
Manual soldering: 370°C, 3sec. Max
- 4.Environmental Characteristics
Operating temperature: -40°C~+85°C
Operating humidity: 10%~+95%RH



NANO SIM CARD	
Pin No.	ASSIGNMENT
C1	VCC(SUPPLY VOLTAGE)
C2	RST(RESET SIGNAL)
C3	CLK(CLOCK SIGNAL)
C5	GND
C6	VPP(VARIABLE SUPPLY VOLTAGE)
C7	I/O(DATA INPUT/OUTPUT)

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area: Gold plated
3	SHELL	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X ±0.35	X* ±5°	MUP MUP INDUSTRIAL CO.,LTD. NAME: NANO-SIM Card Connector MODEL NO: MUP-C7082-04 TYPE: H1.35mm 6PIN Without Switch Pin/ outside solder
X.X ±0.25	X.X* ±4°	
X.XX ±0.15	X.XX* ±3°	
X.XXX ±0.10	X.XXX* ±2°	

PROJ.	UNIT mm	SCALE 1:1	DRAWN Henry Mar.12.2019	DWG NO.: DWG-C7082-04-01
CUSTOMER DRAWING			CHECKED Henry Mar.12.2019	SHEET 1/1
			APPROVAL Simon Mar.12.2019	REVISION 2

